

IN THE SPECIFICATION:

Please replace paragraphs [0002], [0005], and [0017] with the following amended paragraphs:

[0002] FIG. 1 is a side view illustrating a prior art system 100 used to cool a processor 112. As shown, system 100 typically includes a heat sink assembly 104, which further includes a fan 106, walls 109 (illustrated in FIG. 2), fins 115 (illustrated in FIG. 2), bottom surface 111 and a thermal adhesive 110, which is configured to thermally couple heat sink assembly 104 to processor 112. Thermal adhesive 110 has thermal properties that facilitate transferring heat generated by processor 112 to the bottom surface 111 of heat sink assembly 104. As also shown in FIG. 1, system 100 may include a heat sink lid 102, which, among other things, prevents particles and other contaminants from entering fan 106 and air blown from fan 106 from escaping the system 100, as described herein. The heat sink lid 102, together with the walls 109, fins 115, and bottom surface 111 of the heat sink assembly 104, define a plurality of air channels 108.

[0005] FIG. 2 is an isometric view illustrating heat sink assembly 104 of FIG. 1. This view provides a better perspective of fan 106, fins 115, walls 109 and air channels 108. Persons skilled in the art will understand that air channels 108 typically are configured to direct air blown from fan 106, over bottom surface 111, to the external environment in a manner that most efficiently removes heat from processor 112 (not shown).

[0017] As further illustrated in FIG. 5, the uncovered portion of air channels 108, defined by walls 109 fins 115, and the bottom surface 111 of the heat sink assembly 104, replaces the solid surface of a conventional heat sink lid, such as metal heat sink lid 102, that reflects sound waves propagating through the air channels 108. Thus, incorporating the heat sink lid 400 eliminates the reflective surface, thereby preventing a standing wave, such as standing wave pattern 300, from forming in air channels 108

during operation. For this reason, a system incorporating the heat sink lid 400, as opposed to prior art heat sink lid 102, produces less air flow noise during operation.